

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of: **Kuei-Wu Huang, et al.**

Serial No.: **10/687,713**

Group Art Unit: **1765**

Filed: **October 17, 2003**

Examiner: **L. Vinh**

For: **SURFACE TREATED LOW-K DIELECTRIC AS DIFFUSION BARRIER  
FOR COPPER METALLIZATION**

**PETITION FOR EXTENSION**  
**37 C.F.R. §1.136(a)**

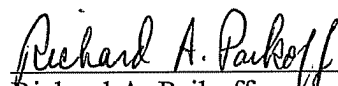
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant requests retroactive extension of the term for response to the official action mailed January 6, 2006 (Paper No. 010406), to and including the filing of the accompanying Amendment and Response. The required fee in the amount of \$120 (large entity rate) for the requested one-month extension should be charged to Deposit Account No. 04-1679.

Respectfully submitted,

Date 5/5/06



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